

**XX#### REV E1 Bill of Materials**

<b>Designator</b>	<b>Quantity</b>	<b>Value</b>	<b>PartNumber</b>	<b>Manufacturer</b>	<b>Description</b>	<b>PackageReference</b>
C1	1	560uF	LLG2W561MELB50	Nichicon	CAP, AL, 560 $\mu$ F, 450 V, +/- 20%, TH	D30xL50mm
TP1, TP2	2		3620-1-32-15-00-00-08-0	Mill-Max	Edge-Mount Pin, Gold	Edge-Mount Pin

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